

DH188 Hall-effect sensor is a temperature stable, stress sensor. Superior high-temperature performance is made possible through a dynamic offset cancellation that utilizes chopper-stabilization. This method reduces the offset voltage normally caused by device over molding, temperature dependencies, and thermal stress.

DH188 includes the following on a single silicon chip: voltage regulator, Hall voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, Advanced DMOS wafer fabrication processing is used to take advantage of low-voltage requirements, component matching, very low input-offset errors, and small component geometries.

This device requires the presence of both south and north polarity magnetic fields for operation. In the presence of a south polarity field of sufficient strength, the device output sensor on, and only switches off when a north polarity field of sufficient strength is present.

DH188 is rated for operation between the ambient temperatures -40°C and 85°C for the E temperature range, and -40°C to 125°C for the K temperature range. The two package styles available provide magnetically optimized solutions for most applications. Package SO is an SOT-23, a miniature low-profile surface-mount package, while package UA is a three-lead ultra mini SIP for through-hole mounting.

Packages is Halogen Free standard and which have been verified by third party lab.

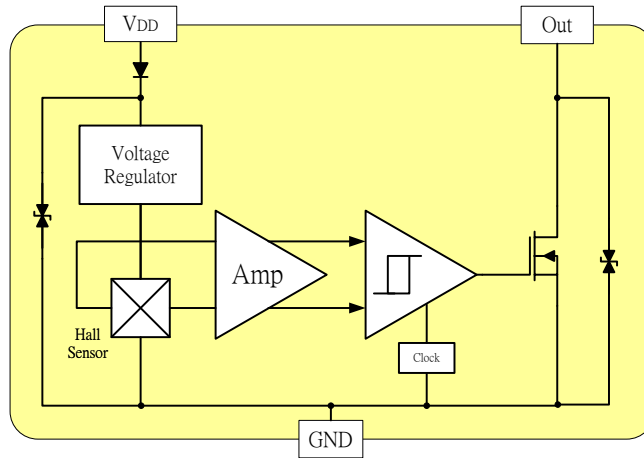
Features and Benefits

- DMOS Hall IC Technology.
- Reverse bias protection on power supply pin.
- Chopper stabilized amplifier stage.
- Optimized for BLDC motor applications.
- Reliable and low shifting on high Temp condition.
- Good ESD Protection.
- 100% tested at 125°C for K.
- Custom sensitivity / Temperature selection are available.

Applications

- High temperature Fan motor
- 3 phase BLDC motor application
- Speed sensing
- Position sensing
- Current sensing
- Revolution counting
- Solid-State Switch
- Linear Position Detection
- Angular Position Detection
- Proximity Detection
- High ESD Capability

Functional Diagram



Absolute Maximum Ratings At ($T_a=25\text{ }^\circ\text{C}$)

Characteristics		Values	Unit
Supply voltage, (V_{DD})		28	V
Output Voltage, (V_{out})		28	V
Reverse voltage, (V_{DD})		-28	V
Magnetic flux density		Unlimited	Gauss
Output current, (I_{out})		50	mA
Operating Temperature Range, (T_a)	“E” version	-40 to +85	$^\circ\text{C}$
	“K” version	-40 to +125	$^\circ\text{C}$
Storage temperature range, (T_s)		-65 to +150	$^\circ\text{C}$
Maximum Junction Temp, (T_j)		150	$^\circ\text{C}$
Thermal Resistance	(θ_{ja}) UA / SO	206 / 543	$^\circ\text{C}/\text{W}$
	(θ_{jc}) UA / SO	148 / 410	$^\circ\text{C}/\text{W}$
Package Power Dissipation, (P_D) UA / SO		606 / 230	mW

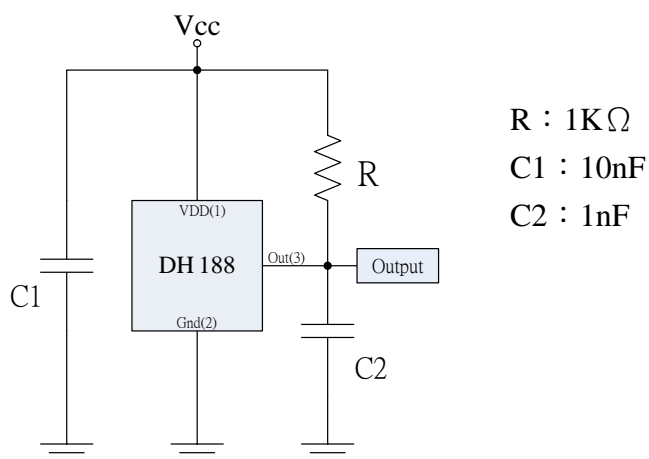
Note: Do not apply reverse voltage to V_{DD} and V_{OUT} Pin, It may be caused for Miss function or damaged device.

Electrical Specifications

DC Operating Parameters : $T_A = +25^\circ\text{C}$, $V_{DD} = 12\text{V}$

Parameters	Test Conditions	Min	Typ	Max	Units
Supply Voltage, (V_{DD})	Operating	2.5		24.0	V
Supply Current, (I_{DD})	B<BOP			5.0	mA
Output Saturation Voltage, (V_{sat})	$I_{out} = 20\text{mA}$, B>BOP			400.0	mV
Output Leakage Current, (I_{off})	IOFF B<BRP, $V_{OUT} = 12\text{V}$			10.0	uA
Internal Oscillator Chopper Frequency, (f_{osc})			69		kHz
Output Rise Time, (T_R)	$R_L = 1.1\text{K}\Omega$, $C_L = 20\text{pF}$		0.04	0.45	uS
Output Fall Time, (T_F)	$R_L = 820\Omega$; $C_L = 20\text{pF}$		0.18	0.45	uS
Electro-Static Discharge	HBM	4			KV
Operate Point, (B_{OP})	UA(SO)	5(-25)		25(-5)	Gauss
Release Point, (B_{RP})	UA(SO)	-25(5)		-5(25)	Gauss
Hysteresis, (B_{HYS})			30		Gauss

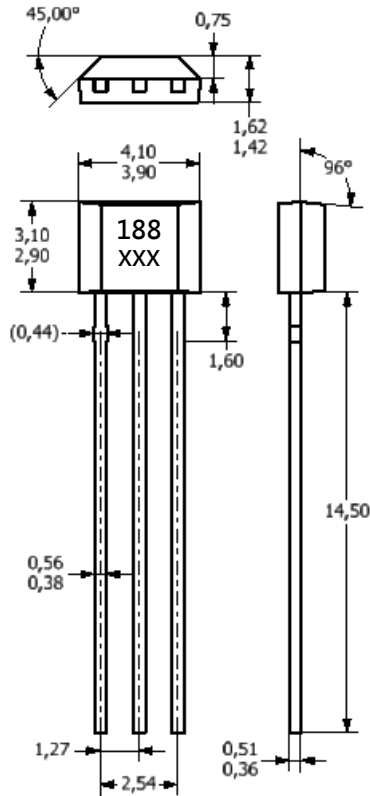
Typical application circuit



Sensor Location, Package Dimension and Marking

Package

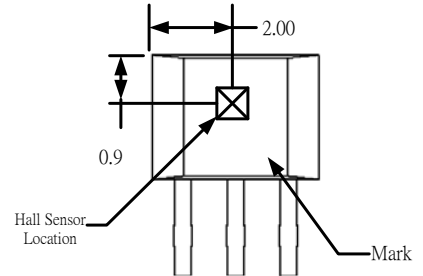
UA Package



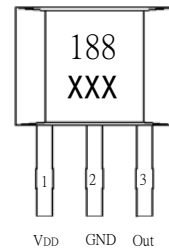
NOTES:

- 1).Controlling dimension: mm
- 2).Leads must be free of flash and plating voids
- 3).Do not bend leads within 1 mm of lead to package interface.
- 4).PINOUT:
Pin 1 V_{DD}
Pin 2 GND
Pin 3 Output

Hall Chip location

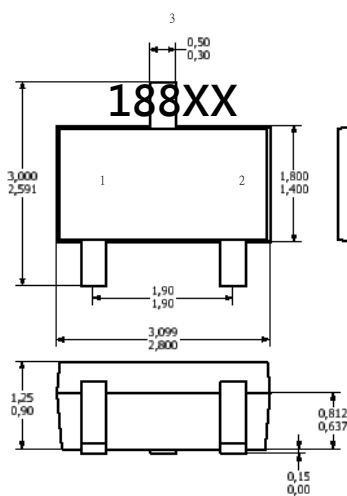


Output Pin Assignment (Top view)



SO Package

(Top View)



NOTES:

1. PINOUT (See Top View at left :)
Pin 1 V_{DD}
Pin 2 Output
Pin 3 GND
2. Controlling dimension: mm
3. Lead thickness after solder plating will be 0.254mm maximum

Hall Plate Chip Location

(Bottom view)

